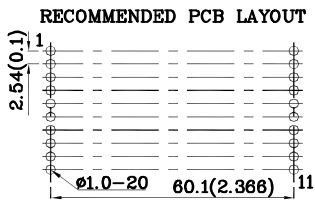
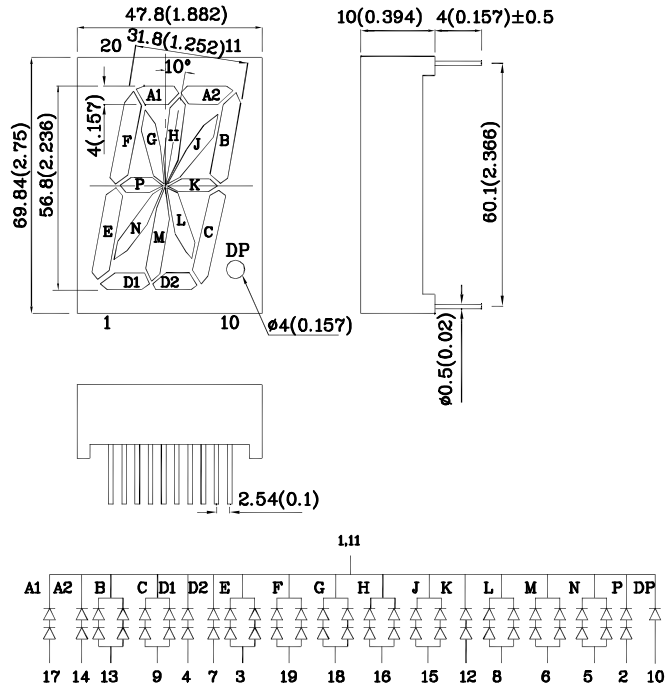


Features

- Low power consumption
- Robust package
- I.C. Compatible
- Standard configuration: Gray face w/ white segments
- Optional black face provides superior color contrast
- RoHS Compliant



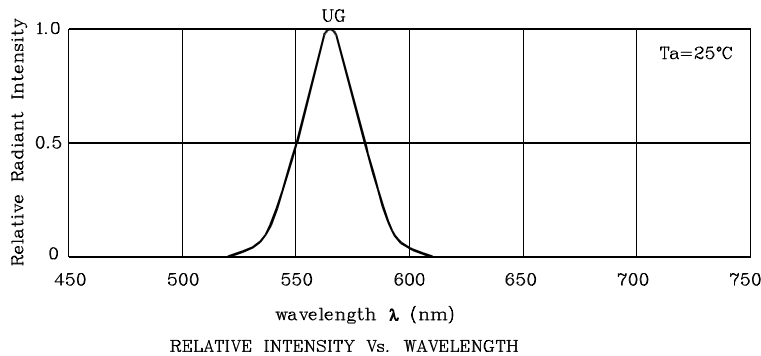
Package Schematics



Notes:

1. All dimensions are in millimeters (inches), Tolerance is ±0.25(0.01") unless otherwise noted.
2. Specifications are subject to change without notice.

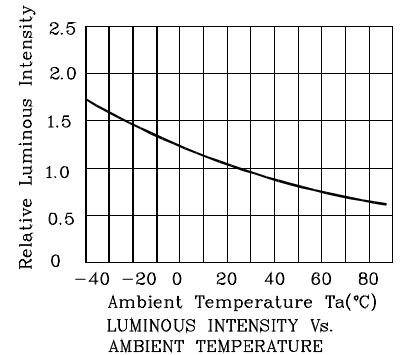
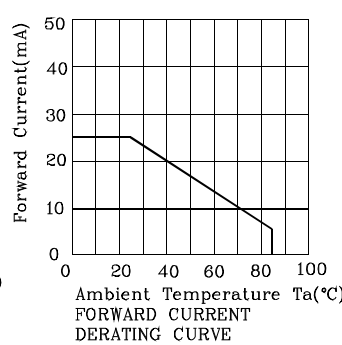
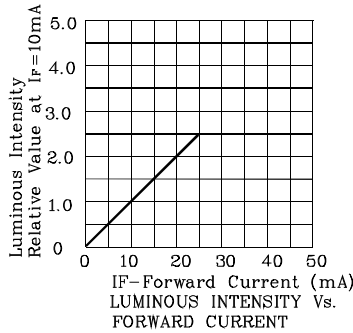
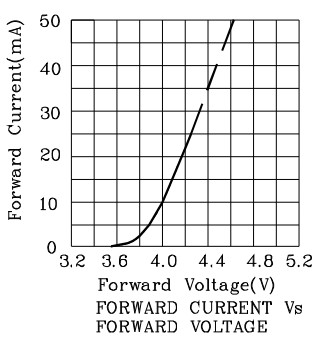
Part Number	Emitting Color	Emitting Material	Luminous Intensity (I _F =10mA) ucd		Wavelength nm λP	Description
			min.	typ.		
XAUG60C	Green	GaP	5600	13990	565	Common Cathode, Rt. Hand Decimal.



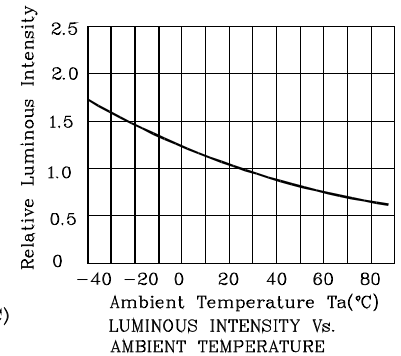
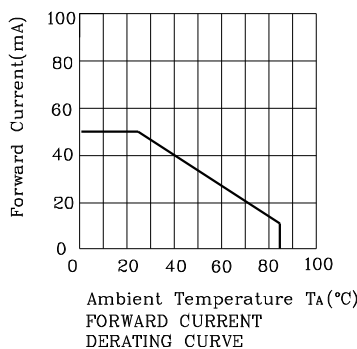
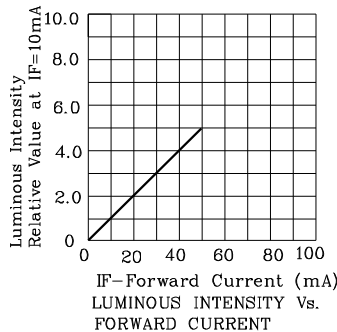
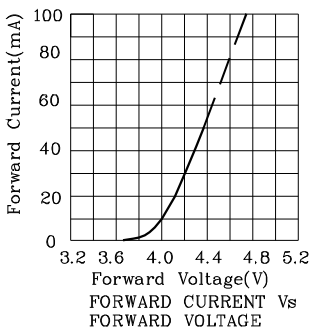
Absolute maximum ratings (TA=25°C)		UR (GaAsP/GaP)	Unit
Reverse Voltage	A1,A2,D1, D2,P,K	VR	5
	B,C,E,F,G, H,J,L,M,N		5
	DP		5
Forward Current	A1,A2,D1, D2,P,K	IF	25
	B,C,E,F,G, H,J,L,M,N		50
	DP		25
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	A1,A2,D1, D2,P,K	iFS	140
	B,C,E,F,G, H,J,L,M,N		280
	DP		140
Power Dissipation	A1,A2,D1, D2,P,K	PD	125
	B,C,E,F,G, H,J,L,M,N		250
	DP		62.5
Operating Temperature		TA	-40 ~ +85
Storage Temperature		Tstg	-40 ~ +85
Lead Solder Temperature [2mm Below Package Base]		260°C For 3~5 Seconds	

Operating Characteristics (TA=25°C)		UR (GaAsP/GaP)	Unit
Forward Voltage (Typ.) (IF=10mA)	A1,A2,D1,D2, P,K	VF	4
	B,C,E,F,G,H, J,L,M,N		2
	DP		2
Forward Voltage (Max.) (IF=10mA)	A1,A2,D1,D2, P,K	VF	5
	B,C,E,F,G,H, J,L,M,N		2.5
	DP		2.5
Reverse Current (Max.) (VR=5V)	A1,A2,D1,D2, P,K	IR	10
Reverse Current (Max.) (VR=5V)	B,C,E,F,G,H, J,L,M,N		20
Reverse Current (Max.) (VR=5V)	DP		10
Wavelength of Peak Emission (Typ.) (IF=10mA)		λP	565 nm
Wavelength of Dominant Emission (Typ.) (IF=10mA)		λD	568 nm
Spectral Line Full Width At Half- Maximum (Typ.) (IF=10mA)		Δλ	30 nm
Capacitance (Typ.) (VF=0V, f=1MHz)		C	15 pF

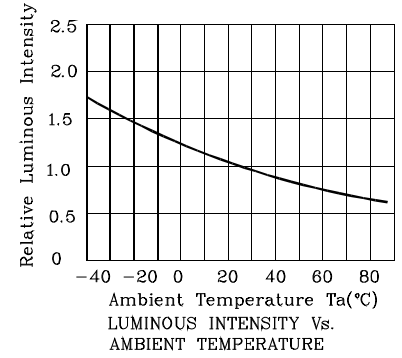
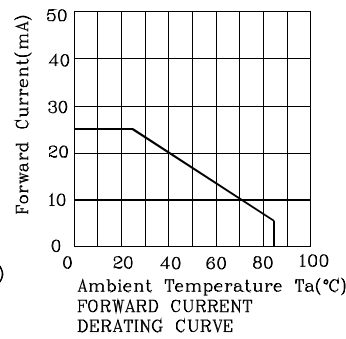
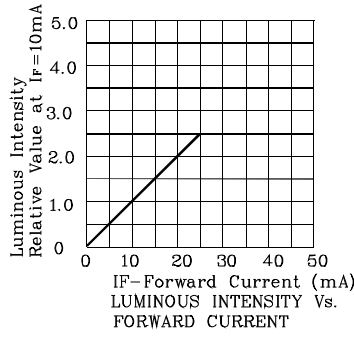
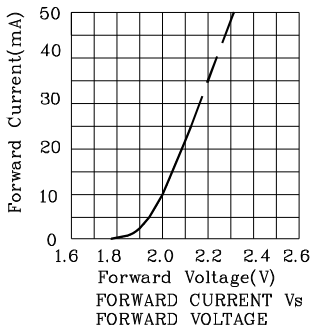
❖ UG



Note:the curves are on the segment a1,a2,d1,d2,p,k.

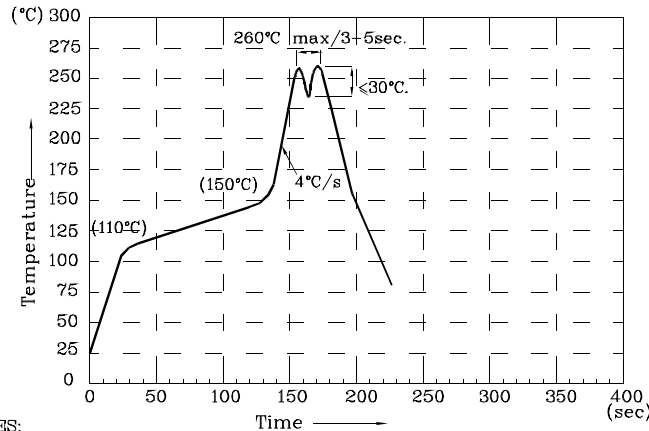


Note:the curves are on the segment b,c,e,f,g,h,j,l,m,n.



Note:the curves are on the DP.

Wave Soldering Profile for Thru-Hole Products (Pb-Free Components)



NOTES:

- 1.Recommend the wave temperature 245°C~260°C.The maximum soldering temperature should be less than 260°C.
- 2.Do not apply stress on epoxy resins when temperature is over 85°C.
- 3.The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
- 4.During wave soldering, the PCB top-surface temperature should be kept below 105°C.
- 5.No more than once.

Remarks:

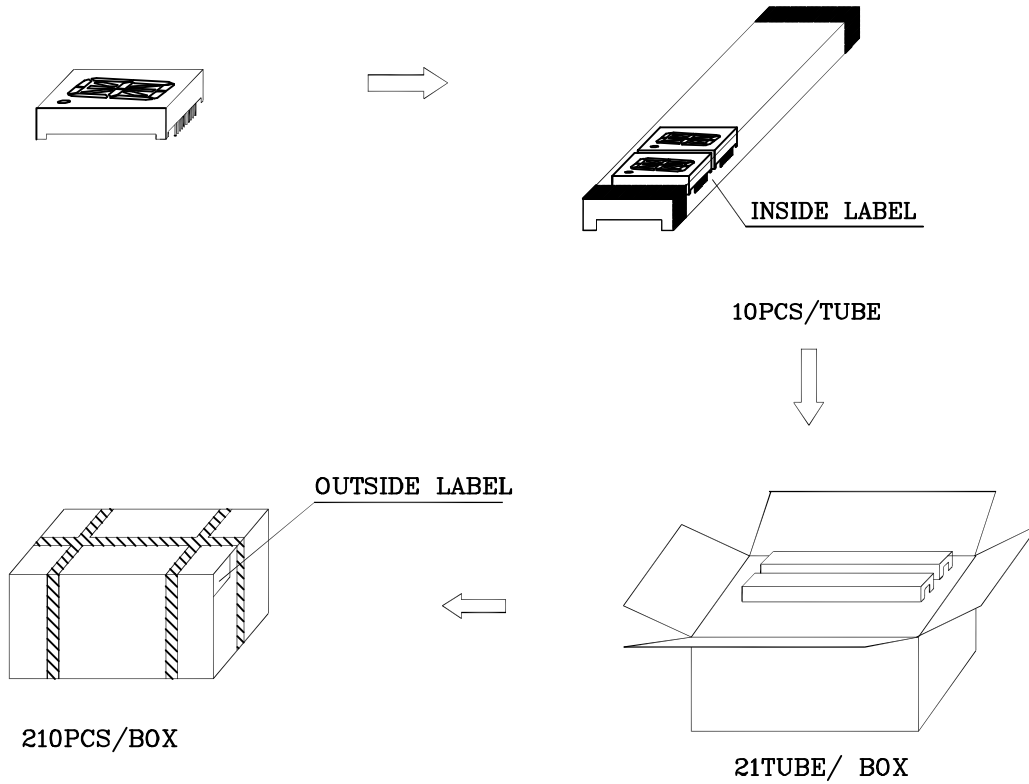
If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm
2. Luminous Intensity / Luminous Flux: +/-15%
3. Forward Voltage: +/-0.1V

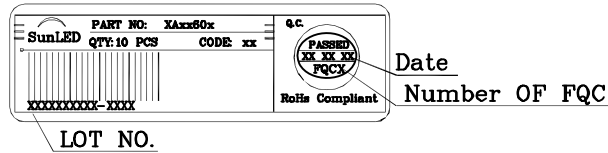
Note: Accuracy may depend on the sorting parameters.



PACKING & LABEL SPECIFICATIONS



Inside Label On IC-tube



Outside Label On Box

